

L Number	Hits	Search Text	DB	Time stamp
	2	float and zervigon.xa.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2003/02/06 10:26
	26067	float\$ same (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:26
	596507	((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:29
	5524	(float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/21 10:25
	21	((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and "first electrode" and DC and AC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:33
	15	((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and "upper electrode" and DC and AC not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and "first electrode" and DC and AC)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:40
	28	((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and (electrode same (DC and AC) not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and "first electrode" and DC and AC) or (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and "upper electrode" and DC and AC not (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and "first electrode" and DC and AC) or (((float\$ same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and "first electrode" and DC and AC)))	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM_TDB	2002/08/20 17:53



	111	((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and AC and DC	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2002/08/21 11:51
	24	(((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and AC and DC) and switch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2002/08/21 11:56
	2	5897752.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB USPAT	2002/08/21 11:56
	6	((("5316646") or ("5316645") or ("5202008") or ("5114556") or ("4038171") or ("3410775"))).PN.	USPAT	2002/08/21 11:59
	87	(((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and AC and DC) not (((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and AC and DC) and switch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 12:00
	168	((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and switch not (((float\$ and potential) same (wafer or substrate)) and (((c23c016\$.ipc. or c23c014\$.ipc. or h01l021\$.ipc or c23f01\$.ipc.) or ((156/\$).CCLS. OR (118/\$).CCLS. OR (438/\$).CCLS. OR (427/\$).CCLS. OR (219/\$).CCLS.))) and AC and DC) and switch	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 14:02
	2	6220201.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2002/08/21 14:25
	9	((("6033482") or ("6406925") or ("5942042") or ("6346428") or ("5897752") or ("6379576") or ("6237527") or ("6220201") or ("5980687") or ("5980687"))).PN.	USPAT	2002/08/21 14:25
	2	5980687.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 10:39
	1	us-20030017709-.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 12:06
	3265	(wafer or substrate) same (conduction and interface)	EPO; JPO; DERWENT; IBM TDB USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 12:07
	1271	(wafer or substrate) with (conduction and interface)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 12:08
	78	(wafer or substrate) with (conduction and interface and roughness)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 12:14
	1	us-20030017709-.did.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 12:22

	2	5810933.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 13:12
	2	5980687.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 13:53
	1974	((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 13:57
	1113	(((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 13:59
	864	(((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower) and (wafer or substrate)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 13:59
	807	((((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower) and (wafer or substrate)) and power	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 14:00
	403	((((((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower) and (wafer or substrate)) and power) and khz and mhz	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 14:03
	74	(((((((HF and LF) or ((high-frequency or "high frequency") and (low-frequency or "low frequency")))) and plasma and (electrode or anode or cathode)) and upper and lower) and (wafer or substrate)) and power) and khz and mhz) and (118/723e.ccls. or 156/345.43.ccls. or 156/345.44.ccls. or 156/345.46.ccls.)	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 14:46
	2	5810933.pn.	USPAT; US-PGPUB; EPO; JPO; DERWENT; IBM TDB	2003/02/06 14:46